

PRELIMINARY SPEC

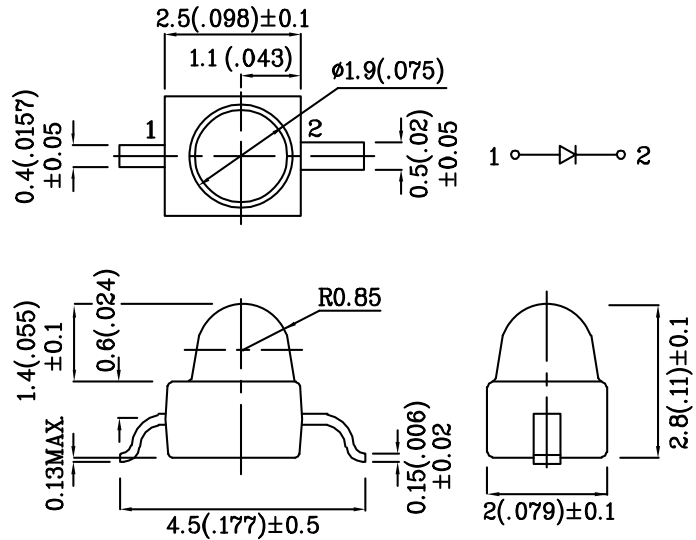
**Features**

- SUBMINIATURE PACKAGE.
- GULL WING LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



Notes:

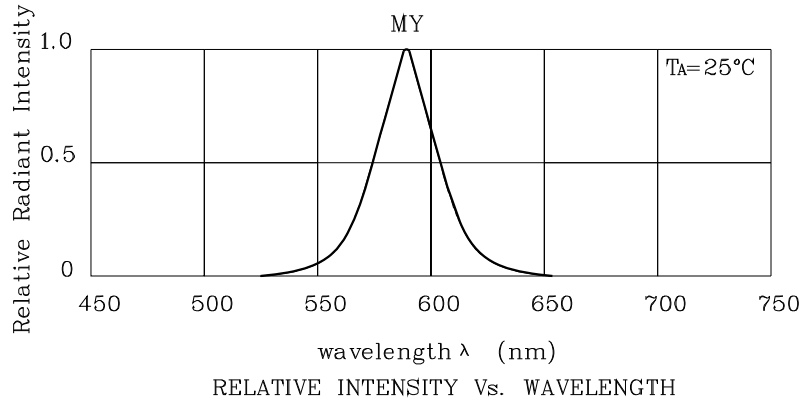
1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
3. Specifications are subject to change without notice.



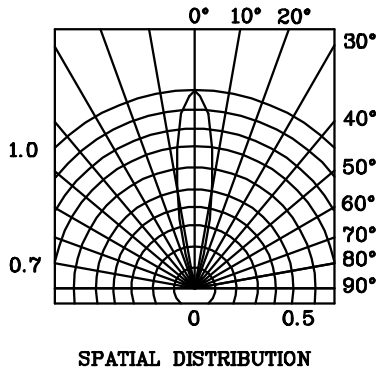
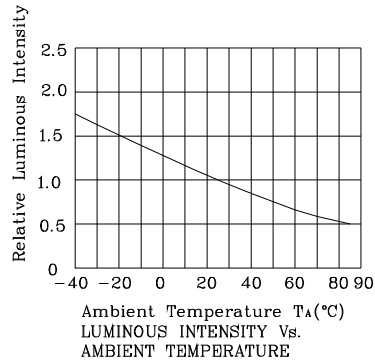
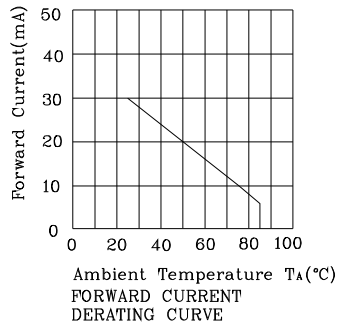
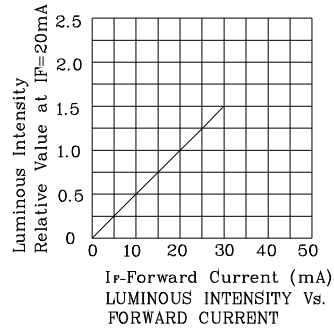
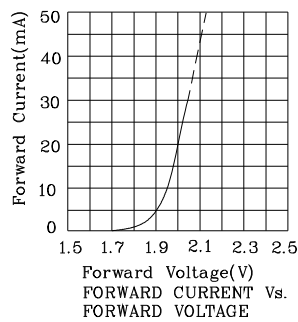
Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )		MY (InGaAlP)	Unit
Reverse Voltage	$V_R$	5	V
Forward Current	$I_F$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{FS}$	150	mA
Power Dissipation	$P_T$	75	mW
Operating Temperature	$T_A$	-40 ~ +85	°C
Storage Temperature	$T_{stg}$	-40 ~ +85	

Operating Characteristics ( $T_A=25^\circ\text{C}$ )		MY (InGaAlP)	Unit
Forward Voltage (Typ.) ( $I_F=20\text{mA}$ )	$V_F$	2.0	V
Forward Voltage (Max.) ( $I_F=20\text{mA}$ )	$V_F$	2.5	V
Reverse Current (Max.) ( $V_R=5\text{V}$ )	$I_R$	10	$\mu\text{A}$
Wavelength Of Peak Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_P$	590	nm
Wavelength Of Domi- nant Emission (Typ.) ( $I_F=20\text{mA}$ )	$\lambda_D$	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) ( $I_F=20\text{mA}$ )	$\Delta\lambda$	28	nm
Capacitance (Typ.) ( $V_F=0\text{V}$ , $f=1\text{MHz}$ )	$C$	25	pF

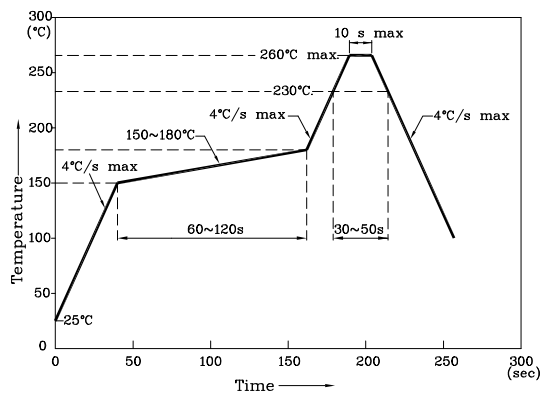
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ( $I_F=20\text{mA}$ ) mcd		Wavelength nm $\lambda_P$	Viewing Angle $2\theta$ 1/2
				min.	typ.		
XZMY46W-3	Yellow	InGaAlP	Water Clear	900	1495	590	20°
Published Date : JAN 21,2008      Drawing No : XDSA1725      V7      Checked : B.L.LIU      P.1/4							



❖ MY



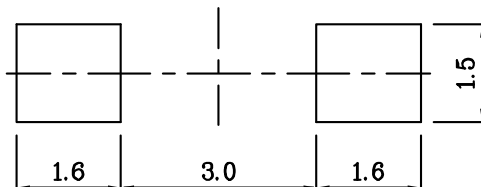
Reflow Soldering Profile For Lead-free SMT Process.



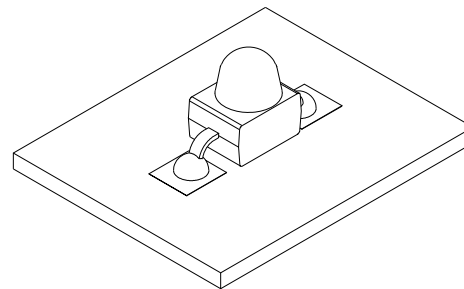
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

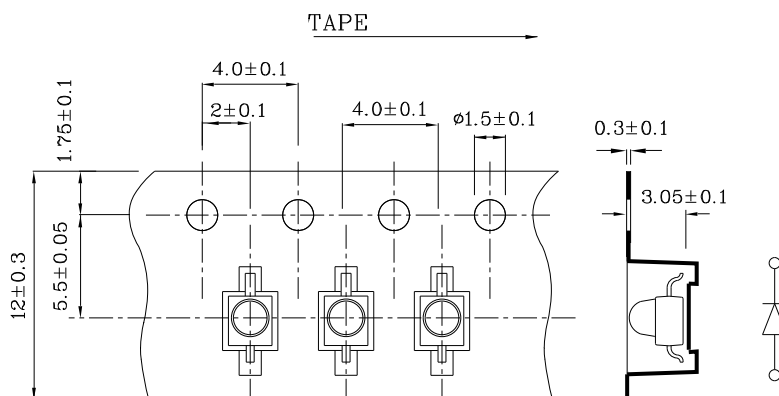
❖ Recommended Soldering Pattern  
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

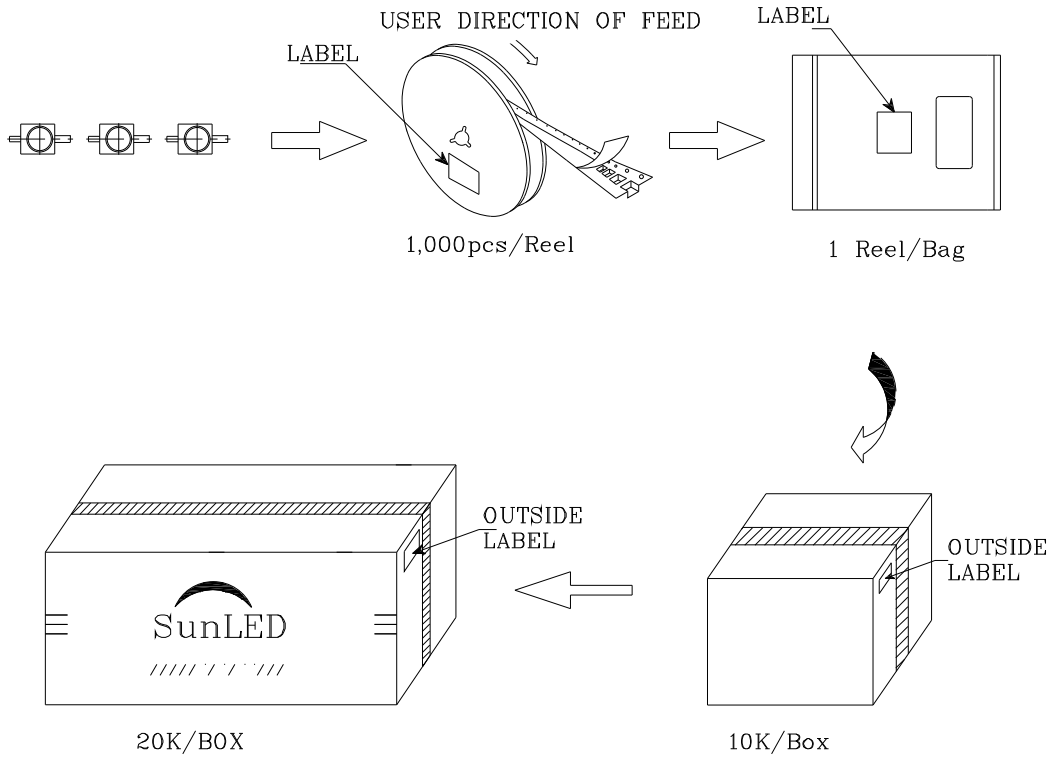

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

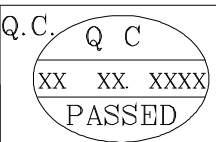

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**XZMY46W-3**

	
P/NO : XZxxx46x-3	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	